# **GSM4320XF**

## **GSM4320XF**

## Preliminary Specification

## **40V N-Channel MOSFET**

#### Absolute Maximum Ratings (T<sub>A</sub> = 25°C unless otherwise specified)

| Symbol           | Parameter                                     |                       | Value       | Unit |  |
|------------------|---|-----------------------|-------------|------|--|
| V <sub>DSS</sub> | Drain-Source Voltage                          |                       | 40          | V    |  |
| V <sub>GSS</sub> | Gate-Source Voltage                           |                       | ±20         | V    |  |
|                  | Continuous Drain Current<br>(Silicon Limited) | T <sub>C</sub> =25°C  | 168         | A    |  |
| lo               |   | T <sub>C</sub> =100°C | 106         |      |  |
|                  | Continuous Drain Current<br>(Package Limited) |                       | 100         |      |  |
| I <sub>DM</sub>  | Pulsed Drain Current <sup>1</sup>             |                       | 400         | Α    |  |
| D .              | Power Dissipation                             | T <sub>C</sub> =25°C  | 113         | w    |  |
| P <sub>D</sub>   |   | T <sub>C</sub> =100°C | 45          |      |  |
| R <sub>eJC</sub> | Thermal Resistance-Junction to Case           |                       | 1.1         | °C/W |  |
| R <sub>θJA</sub> | Thermal Resistance-Junction to Ambient        |                       | 62          | °C/W |  |
| TJ               | Operating Junction Temperature Range          |                       | -55 to +150 | °C   |  |
| Тѕтс             | Storage Temperature Range                     |                       | -55 to +150 | °C   |  |

#### NOTE:

#### Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

| Symbol              | Parameter                      | Test Conditions  | Min. | Тур. | Max. | Unit |  |
|---------------------|--------------------------------|--|------|------|------|------|--|
|                     | Static Characteristics         |  |      |      |      |      |  |
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage | V <sub>GS</sub> =0V, I <sub>D</sub> =250µA               | 40   | -    | -    | V    |  |
| IDSS                | Drain-Source Leakage Current   | V <sub>DS</sub> =40V, V <sub>GS</sub> =0V                | -    | -    | 1    | μA   |  |
| Igss                | Gate-Source Leakage Current    | V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V               | -    | -    | ±100 | nA   |  |
| V <sub>GS(th)</sub> | Gate Threshold Voltage         | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA | 1.2  | -    | 2.5  | V    |  |
|                     | Busin Course On Busintan       | V <sub>GS</sub> =10V, I <sub>D</sub> =20A                | -    | -    | 2    |      |  |
| R <sub>DS(ON)</sub> | Drain-Source On-Resistance     | V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A               | -    | -    | 3.4  | mΩ   |  |
| VsD                 | Diode Forward Voltage          | V <sub>GS</sub> =0V, I <sub>S</sub> =1A                  | -    | -    | 1    | V    |  |



<sup>1.</sup> Single pulse width is limited by max junction temperature.

### Packages & Pin Assignments

|     | DFN5X6-8L |             |     | Equivalent | Circuit     |  |  |
|-----|-----------|-------------|-----|------------|-------------|--|--|
|     | 1 2 3 4   |             | G S |            |             |  |  |
| Pin | Symbol    | Description | Pin | Symbol     | Description |  |  |
| 1   | S         | Source      | 8   | D          | Drain       |  |  |
| 2   | S         | Source      | 7   | D          | Drain       |  |  |
| 3   | S         | Source      | 6   | D          | Drain       |  |  |
| 4   | G         | Gate        | 5   | D          | Drain       |  |  |



#### NOTICE

- Globaltech Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Globaltech Semiconductor products described or contained herein. Globaltech Semiconductor products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. Globaltech Semiconductor makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- Information furnished is believed to be accurate and reliable. However Globaltech Semiconductor assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties, which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Globaltech Semiconductor. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information without express written approval of Globaltech Semiconductor.

#### **CONTACT US**

| GS Headquarter |   |  |  |  |
|----------------|---|--|--|--|
|                | 4F, NO.43-1, Lane 11, Sec. 6, Minquan E. Rd Neihu District, Taipei City 114761, Taiwan (R.O.C). |  |  |  |
| 6              | 886-2-2657-9980   |  |  |  |
| <i>Q</i> :•\   | 886-2-2657-3630   |  |  |  |
| @              | sales_twn@gs-power.com  |  |  |  |

| RD Division                            |                                      |  |  |  |
|--|--------------------------------------|--|--|--|
| \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ | 824 Bolton Drive Milpitas. CA. 95035 |  |  |  |
| £                                      | 1-408-457-0587                       |  |  |  |

